Listing of Claims:

1. (Previously Presented) A holding and conveyance jig for detachably holding and conveying a printed circuit board on which electronic components are mounted, said jig comprising:

a plate which has a weak-adherence adhesive pattern on a surface of the plate; wherein:

said printed circuit board has a conductive portion and a non-conductive portion on a surface of the printed circuit board, and said printed circuit board is placed and held on the surface of said plate,

said weak-adherence adhesive pattern is formed at a position corresponding to said non-conductive portion and detachably holds the printed circuit board at said non-conductive portion, and

said weak-adherence adhesive pattern has a plurality of thickness regions differing in thickness from the surface of said plate according to thickness regions of the printed circuit board.

2. (Currently Amended) A holding and conveyance jig for detachably holding and conveying a printed circuit board on which electronic components are mounted, said jig comprising:

a plate which has a weak-adherence adhesive layer on a surface of the plate; wherein:

said printed circuit board has a conductive portion and a non-conductive portion on a surface of the printed circuit board, and said printed circuit board is placed and held on the surface of said plate,

a weak-adherence adhesive pattern subjected to surface roughening is formed on a surface of said weak-adherence adhesive layer at a position corresponding to said conductive portion, said weak-adherence adhesive layer [[and]] detachably holds the printed circuit board at said non-conductive portion, and

said weak-adherence adhesive ~~pattern~~ layer has a plurality of thickness regions differing in thickness from the surface of said plate according to thickness regions of the printed circuit board.

Claim 3 (Canceled).

4. (Previously Presented) The holding and conveyance jig according to claim 1, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.

5. (Currently Amended) A holding and conveyance jig for detachably holding and conveying a printed circuit board on which electronic components are mounted, said jig comprising:

a plate which has a weak-adherence adhesive layer on a surface of the plate; wherein:

said printed circuit board has a conductive portion and a non-conductive portion on a surface of the printed circuit board, and said printed circuit board is placed and held on the surface of said plate,

a non-adhesive pattern is formed at a position corresponding to said conductive portion on [[the]] a surface of said weak-adherence adhesive layer,

said weak-adherence adhesive layer detachably holds the printed circuit board at said non-conductive portion, and

said weak-adherence adhesive layer has a plurality of thickness regions differing in thickness from the surface of said plate according to thickness regions of the printed circuit board.

6. (Currently Amended) A method of conveying a printed circuit board comprising the steps of:

providing on said printed circuit board electronic components which are mounted thereon, said printed circuit board having on a surface thereof a conductive portion and a non-conductive portion, and

conveying said printed circuit board while detachably holding said printed circuit board on a surface of a holding and

conveyance jig in which a weak-adherence adhesive pattern is provided on the surface of the jig, in a manner such that said non-conductive portion is placed and held by being restricted to a surface of said weak-adherence adhesive pattern,

wherein said weak-adherence adhesive pattern has a plurality of thickness regions differing in thickness from [[the]] a surface of [[said]] a plate of the jig according to thickness regions of the printed circuit board.

Claims 7-16 (Canceled).

17 (Previously Presented). The holding and conveyance jig according to claim 2, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.

Claims 18 and 19 (Canceled).